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# FAN48611 2.5 MHz, Fixed-Output, Synchronous Tiny Boost® Regulator

## Features

- Input Voltage Range: 2.7 V to 4.8 V
- Output Voltage: 5.25 V
- 350 mA Maximum Output Current
- Internal Synchronous Rectification
- True Load Disconnect
- Short-Circuit Protection
- 9-Bump, 1.215 mm x 1.215 mm, 0.4 mm Pitch, WLCSP
- Three External Components: 2012 1  $\mu$ H Inductor, 0402 Case Size Input / Output Capacitors

## Applications

- Class-D Audio Amplifier and USB OTG Supply
- Boost for Low-Voltage Li-Ion Batteries
- Smart Phones, Tablets, Portable Devices, and Wearables

## Description

The FAN48611 is a low-power boost regulator designed to provide a minimum voltage regulated rail from a standard single-cell Li-Ion battery and advanced battery chemistries. Even below the minimum system battery voltage, the device maintains output voltage regulation. The combination of built-in power transistors, synchronous rectification, and low supply current suit the FAN48611 for battery-powered applications.

The FAN48611 is available in a 9-bump, 0.4 mm pitch, Wafer-Level Chip-Scale Package (WLCSP).

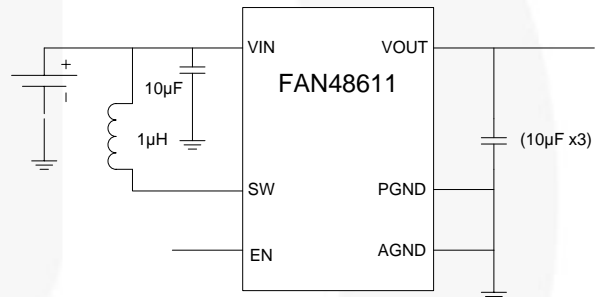


Figure 1. Typical Application

## Ordering Information

Part Number	V <sub>OUT</sub>	Operating Temperature Range	Package	Packing Method	Device Marking
FAN48611UC53X	5.25 V	-40°C to 85°C	9-Bump, 0.4 mm Pitch, Wafer-Level Chip-Scale Package (WLCSP)	Tape and Reel <sup>(1)</sup>	KH

### Note:

1. Tape and reel specifications are available on [www.fairchildsemi.com](http://www.fairchildsemi.com).

## Block Diagram

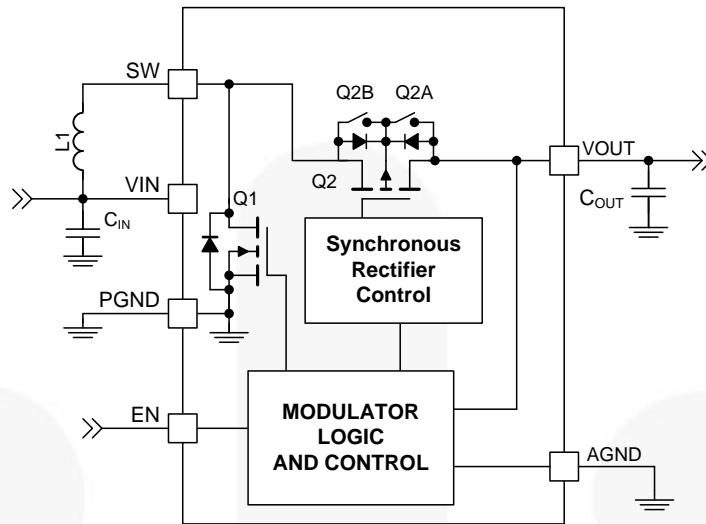


Figure 2. IC Block Diagram

Table 1. Recommended Components

Component	Description	Vendor	Parameter	Typ.	Unit
L1	2012, 1.9 A, 0.6 mm Max. Height	PIXC20120F1R0MDR	L	1	μH
			DCR (Series R)	175	mΩ
C <sub>IN</sub>	20%, 6.3 V, X5R, 0402	C1005X5R0J106M050BC TDK	C	10	μF
C <sub>OUT</sub>	20%, 6.3 V, X5R, 0402	C1005X5R0J106M050BC TDK	C	10	μF

## Pin Configuration

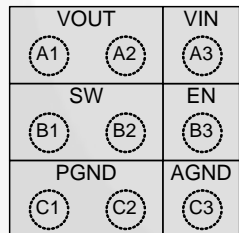


Figure 3. Top View

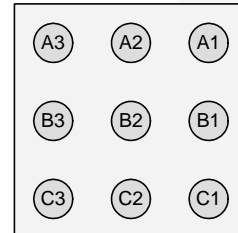


Figure 4. Bottom View

## Pin Definitions

Pin #	Name	Description
A1, A2	VOUT	<b>Output Voltage.</b> This pin is the output voltage terminal; connect directly to C <sub>OUT</sub> .
A3	VIN	<b>Input Voltage.</b> Connect to the Li-Ion battery input power source and the bias supply for the gate drivers.
B1, B2	SW	<b>Switching Node.</b> Connect to inductor.
B3	EN	<b>Enable.</b> When this pin is HIGH, the circuit is enabled. Connection to a logic voltage of 1.8 V and delivery voltage after UVLO typical voltage of 2.2 V is recommended.
C1, C2	PGND	<b>Power Ground.</b> This is the power return for the IC. C <sub>OUT</sub> capacitor should be returned with the shortest path possible to these pins.
C3	AGND	<b>Analog Ground.</b> This is the signal ground reference for the IC. All voltage levels are measured with respect to this pin. Connect to PGND at a single point.

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
V <sub>IN</sub>	Voltage on VIN Pin		-0.3	6.0	V
V <sub>OUT</sub>	Voltage on VOUT Pin			6.0	V
V <sub>SW</sub>	Voltage on SW Node	DC	-0.3	6.0	V
		Transient: 10 ns, 3 MHz	-1.0	8.0	
V <sub>CC</sub>	Voltage on Other Pins		-0.3	6.0 <sup>(2)</sup>	V
ESD	Electrostatic Discharge Protection Level	Human Body Model, ANSI/ESDA/JEDEC JS-001-2012	2		kV
		Charged Device Model per JESD22-C101	2		
T <sub>J</sub>	Junction Temperature		-40	+150	°C
T <sub>STG</sub>	Storage Temperature		-65	+150	°C
T <sub>L</sub>	Lead Soldering Temperature, 10 Seconds			+260	°C

### Note:

2. Lesser of 6.0 V or V<sub>IN</sub> + 0.3 V.

## Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Unit
V <sub>IN</sub>	Supply Voltage	2.7	4.8	V
I <sub>OUT</sub>	Maximum Output Current	350		mA
T <sub>A</sub>	Ambient Temperature	-40	+85	°C
T <sub>J</sub>	Junction Temperature	-40	+125	°C

## Thermal Properties

Junction-to-ambient thermal resistance is a function of application and board layout. This data is measured with four-layer 2s2p boards with vias in accordance to JEDEC standard JESD51. Special attention must be paid not to exceed junction temperature, T<sub>J(max)</sub>, at a given ambient temperature, T<sub>A</sub>.

Symbol	Parameter	Typical	Unit
θ <sub>JA</sub>	Junction-to-Ambient Thermal Resistance	50	°C/W

## Electrical Specifications

Recommended operating conditions, unless otherwise noted, circuit per Figure 1,  $V_{OUT}=5.25\text{ V}$ ,  $V_{IN}=2.7\text{ V}$  to  $4.8\text{ V}$ , and  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$ . Typical values are given  $V_{IN}=3.7\text{ V}$  and  $T_A=25^\circ\text{C}$ .

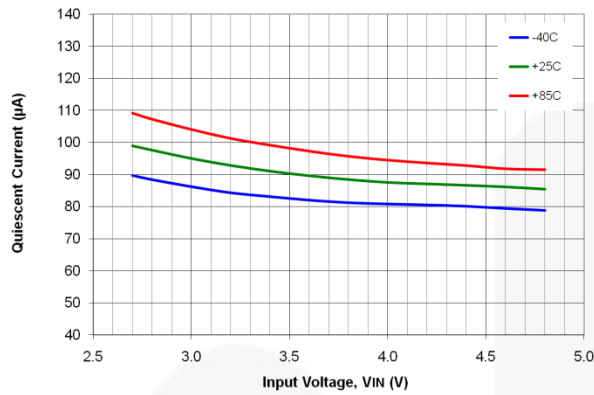
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Power Supply</b>						
$I_Q$	$V_{IN}$ Quiescent Current	$V_{IN}=3.7\text{ V}$ , $I_{OUT}=0$ , $EN=V_{IN}$		90	140	$\mu\text{A}$
		Shutdown: $EN=0$ , $V_{IN}=3.7\text{ V}$ , $V_{OUT}=0\text{ V}$		2.7	10.0	
$V_{UVLO}$	Under-Voltage Lockout	$V_{IN}$ Rising		2.2	2.3	V
$V_{UVLO\_HYS}$	Under-Voltage Lockout Hysteresis			150		mV
<b>Inputs</b>						
$V_{IH}$	Enable HIGH Voltage		1.2			V
$V_{IL}$	Enable LOW Voltage				0.4	V
$I_{PD}$	Current Sink Pull-Down	EN Pin, Logic HIGH		100		nA
$R_{LOW}$	Low-State Active Pull-Down	EN Pin, Logic LOW	200	300	400	k $\Omega$
<b>Outputs</b>						
$V_{REG}$	Output Voltage Accuracy DC <sup>(3)</sup>	Referred to $V_{OUT}$	-2		4	%
$I_{LK\_OUT}$	$V_{IN}$ -to- $V_{OUT}$ Leakage Current	$V_{OUT}=0$ , $EN=0$ , $V_{IN}=2.7\text{ V}$			1	$\mu\text{A}$
$I_{LK}$	$V_{OUT}$ -to- $V_{IN}$ Reverse Leakage Current	$V_{OUT}=5.3\text{ V}$ , $EN=0$ , $V_{IN}=2.7\text{ V}$			3.5	$\mu\text{A}$
$V_{RIPPLE}$	Output Ripple <sup>(4)</sup>	0 mA to 300 mA		30		mV
$V_{TRLOAD}$	Load Transient <sup>(4)</sup>	$I_{LOAD}=0\text{ mA} \leftrightarrow 120\text{ mA}$ , $t_R=t_F=1\ \mu\text{s}$		$\pm 30$		mV
		$I_{LOAD}=0\text{ mA} \leftrightarrow 285\text{ mA}$ , $t_R=t_F=8\ \mu\text{s}$		$\pm 90$		
$V_{TRLINE}$	Line Transient <sup>(4)</sup>	$V_{IN}=3.2\text{ V} \leftrightarrow 3.9\text{ V}$ , $I_{LOAD}=120\text{ mA}$ , $t_R=t_F=7\ \mu\text{s}$		$\pm 50$		mV
$\eta$	Efficiency <sup>(4)</sup>	$V_{IN}=3\text{ V}$ , $I_{LOAD}=5\text{ mA}$		85		%
		$V_{IN}=3\text{ V}$ , $I_{LOAD}=200\text{ mA}$		90		
		$V_{IN}=3.6\text{ V}$ , $I_{LOAD}=200\text{ mA}$		91		
		$V_{IN}=3.6\text{ V}$ , $I_{LOAD}=300\text{ mA}$		92		
<b>Timing</b>						
$f_{SW}$	Switching Frequency	$V_{IN}=3.6\text{ V}$ , $V_{OUT}=5.25\text{ V}$ , $I_{LOAD}=300\text{ mA}$	2.0	2.5	3.0	MHz
$t_{SS}$	Soft-Start EN HIGH to Regulation <sup>(4)</sup>	$V_{IN}=3.0\text{ V}$ , $V_{OUT}=5.25\text{ V}$ , $I_{LOAD}=0\text{ mA}$ , $C_{OUT}=3 \times 10\ \mu\text{F}$		1000		$\mu\text{s}$
$I_{SS}$	Input Peak Current			90	200	mA
$t_{RST}$	FAULT Restart Timer <sup>(4)</sup>			20		ms
<b>Power Stage</b>						
$R_{DS(ON)N}$	N-Channel Boost Switch $R_{DS(ON)}$	$V_{IN}=3.6\text{ V}$ , $V_{OUT}=5.25\text{ V}$		80	130	m $\Omega$
$R_{DS(ON)P}$	P-Channel Sync. Rectifier $R_{DS(ON)}$	$V_{IN}=3.6\text{ V}$ , $V_{OUT}=5.25\text{ V}$		65	115	m $\Omega$
$I_{V\_LIM}$	Boost Valley Current Limit	$V_{OUT}=5.25\text{ V}$		750		mA
$I_{V\_LIM\_SS}$	Boost Soft-Start Valley Current Limit	$V_{IN} < V_{OUT} < V_{OUT\_TARGET}$		375		A
$T_{150T}$	Over-Temperature Protection (OTP)			150		$^\circ\text{C}$
$T_{150H}$	OTP Hysteresis			20		$^\circ\text{C}$

### Notes:

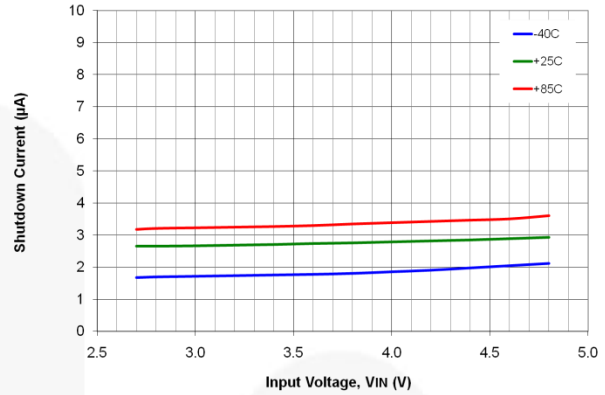
- DC  $I_{LOAD}$  from 0 to 0.35 A.  $V_{OUT}$  measured from mid-point of output voltage ripple. Effective capacitance of  $C_{OUT} \geq 6\ \mu\text{F}$ .
- Guaranteed by design and characterization; not tested in production.

## Typical Performance Characteristics

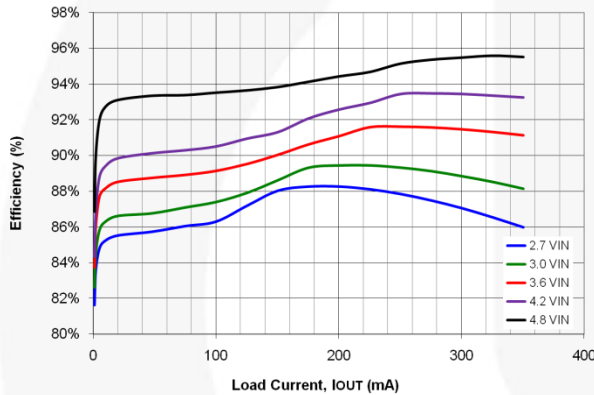
Unless otherwise specified;  $V_{IN} = 3.6\text{ V}$ ,  $V_{OUT} = 5.25\text{ V}$ ,  $T_A = 25^\circ\text{C}$ , and circuit and components according to Figure 1.



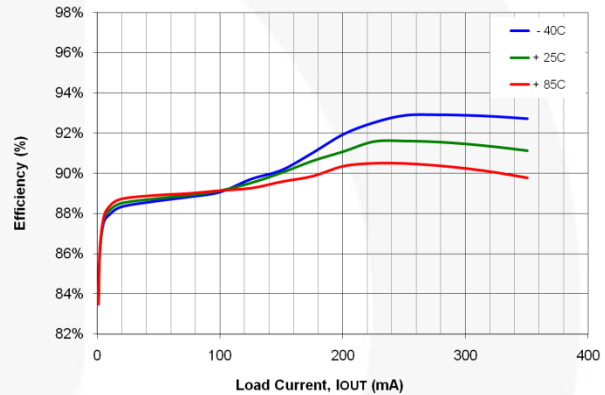
**Figure 5. Quiescent Current vs. Input Voltage and Temperature**



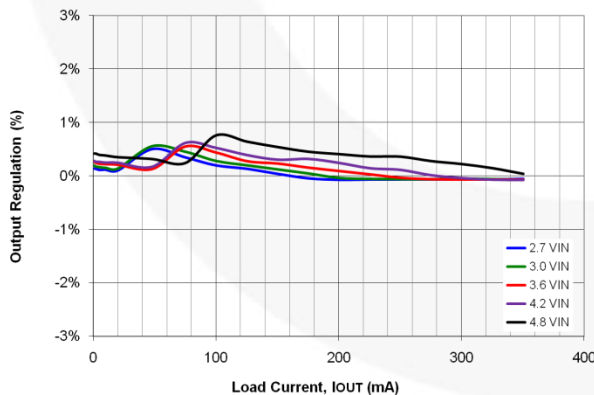
**Figure 6. Shutdown Current vs. Load Current and Temperature**



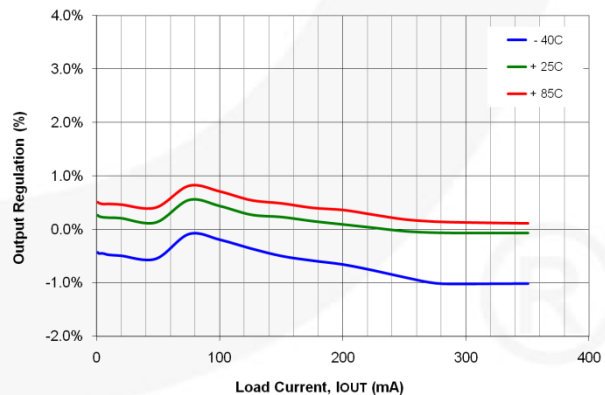
**Figure 7. Efficiency vs. Load Current and Input Voltage**



**Figure 8. Efficiency vs. Load Current and Temperature**



**Figure 9. Output Regulation vs. Load Current and Input Voltage**



**Figure 10. Output Regulation vs. Load Current and Temperature**

## Typical Performance Characteristics

Unless otherwise specified;  $V_{IN} = 3.6\text{ V}$ ,  $V_{OUT} = 5.25\text{ V}$ ,  $T_A = 25^\circ\text{C}$ , and circuit and components according to Figure 1

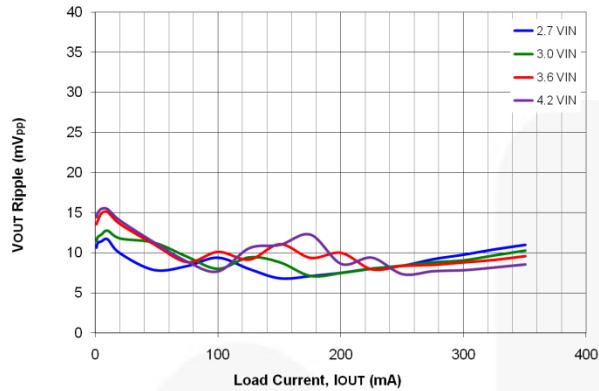


Figure 11. Output Ripple vs. Load Current and Input Voltage

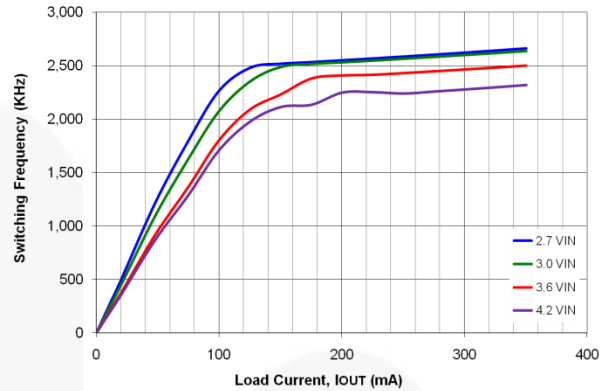


Figure 12. Switching Frequency vs. Load Current and Temperature

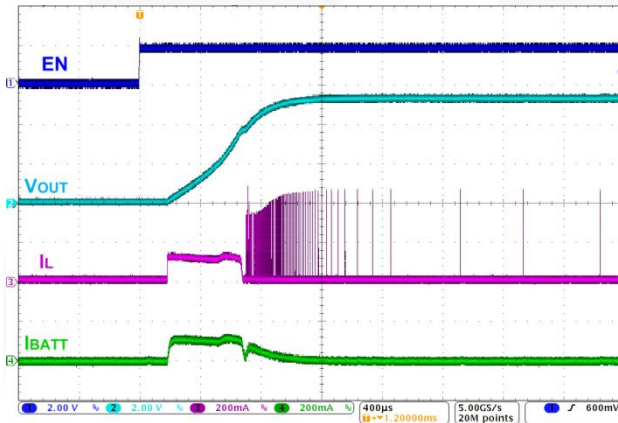


Figure 13. Startup, No Load

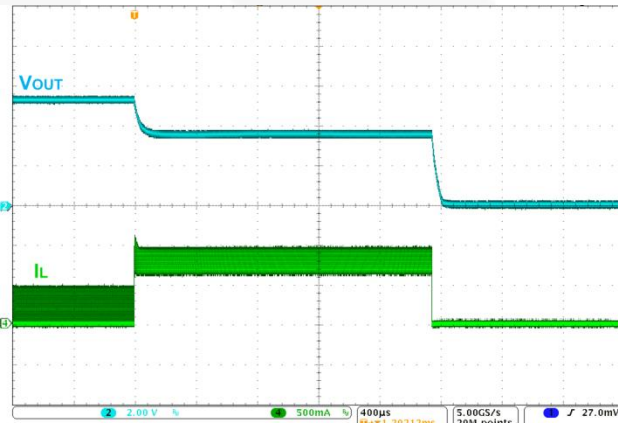


Figure 14. Overload Protection

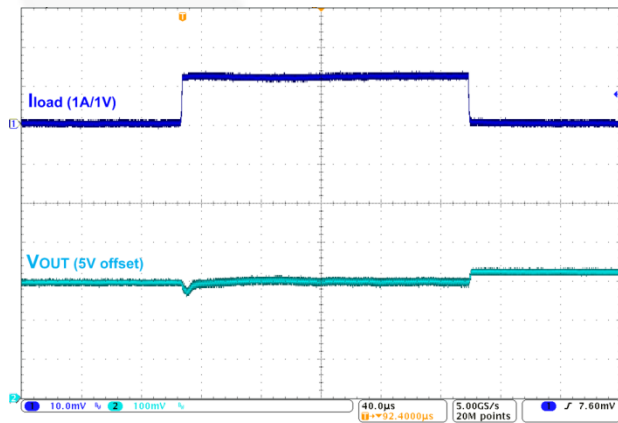


Figure 15. Load Transient, 0 <--> 120 mA, 1  $\mu\text{s}$  Edge

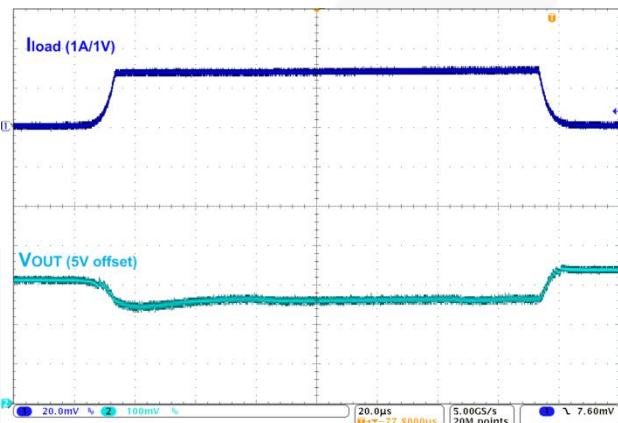


Figure 16. Load Transient, 0 <--> 285 mA, 8  $\mu\text{s}$  Edge

## Typical Characteristics

Unless otherwise specified;  $V_{IN}=3.6\text{ V}$ ,  $V_{OUT}=5.25\text{ V}$ ,  $T_A=25^\circ\text{C}$ , and circuit and components according to Figure 1

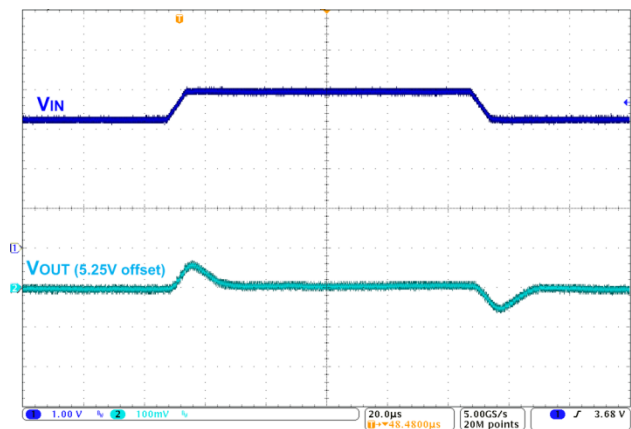


Figure 17. Line Transient, 3.2 <--> 3.9  $V_{IN}$ , 7  $\mu\text{s}$  Edge, 120 mA Load



## Functional Description

FAN48611 is a synchronous boost regulator, typically operating at 2.5 MHz in Continuous Conduction Mode (CCM), which occurs at moderate to heavy load current and low  $V_{IN}$  voltage.

**Table 2. Operating Modes**

Mode	Description	Invoked When:
LIN	Linear Startup	$V_{IN} > V_{OUT}$
SS	Boost Soft-Start	$V_{IN} < V_{OUT} < V_{OUT(TARGET)}$
BST	Boost Mode	$V_{OUT} = V_{OUT(TARGET)}$

### Boost Mode Regulation

The current-mode modulator achieves excellent transient response and smooth transitions between CCM and DCM operation. During CCM operation, the device maintains a switching frequency of about 2.5 MHz. In light-load operation (DCM), frequency is naturally reduced to maintain high efficiency.

### Startup and Shutdown

When EN is LOW, all bias circuits are off and the regulator enters Shutdown Mode. During shutdown, current flow is prevented from VIN to VOUT, as well as reverse flow from VOUT to VIN. It is recommended to keep load current draw below 50 mA until the device successfully executes startup. Table 3 describes the startup sequence.

**Table 3. Boost Startup Sequence**

Start Mode	Entry	Exit	End Mode	Timeout (μs)
LIN1	$V_{IN} > V_{UVLO}$ , EN=1	$V_{OUT} > V_{IN} - 300$ mV	SS	
		TIMEOUT	LIN2	512
LIN2	LIN1 Exit	$V_{OUT} > V_{IN} - 300$ mV	SS	
		TIMEOUT	FAULT	1024
SS	LIN1 or LIN2 Exit	$V_{OUT} = V_{OUT(TARGET)}$	BST	
		OVERLOAD TIMEOUT	FAULT	64

### LIN Mode

When EN is HIGH and  $V_{IN} > V_{UVLO}$ , the regulator attempts to bring  $V_{OUT}$  within 300 mV of  $V_{IN}$  using the internal fixed-current source from VIN (Q2). The current is limited to the  $I_{SS}$  set point, which is typically 90 mA.

The linear charging current is limited to a maximum of 200 mA to prevent any “brownout” situations where the system voltage drops too low.

During LIN1 Mode, if  $V_{OUT}$  reaches  $V_{IN} - 300$  mV, SS Mode is initiated. Otherwise, LIN1 Mode expires after 512 μs and LIN2 Mode is entered.

In LIN2 Mode, the current source is equal to LIN1 current source  $I_{SS}$ , typically 90 mA. If  $V_{OUT}$  fails to reach  $V_{IN} - 300$  mV after 1024 μs, a fault condition is declared and the device waits 20 ms ( $t_{RST}$ ) to attempt an automatic restart.

### Soft-Start (SS) Mode

Upon the successful completion of LIN Mode ( $V_{OUT} \geq V_{IN} - 300$  mV), the regulator begins switching with boost pulses current limited to 50% of nominal level.

During SS Mode, if  $V_{OUT}$  fails to reach regulation during the SS ramp sequence for more than 64 μs, a fault is declared. If a large  $C_{OUT}$  is used, the reference is automatically stepped slower to avoid excessive input current draw.

### Boost (BST) Mode

This is a normal operating mode of the regulator.

### Fault State

The regulator enters Fault State under any of the following conditions:

- $V_{OUT}$  fails to achieve the voltage required to advance from LIN Mode to SS Mode.
- $V_{OUT}$  fails to achieve the voltage required to advance from SS Mode to BST Mode.
- Boost current limit triggers for 2 ms during BST Mode.
- $V_{IN} - V_{OUT} > 300$  mV; this fault can occur only after successful completion of the soft-start sequence.
- $V_{IN} < V_{UVLO}$ .

Once a fault is triggered, the regulator stops switching and presents a high-impedance path between VIN and VOUT. After 20 ms, automatic restart is attempted.

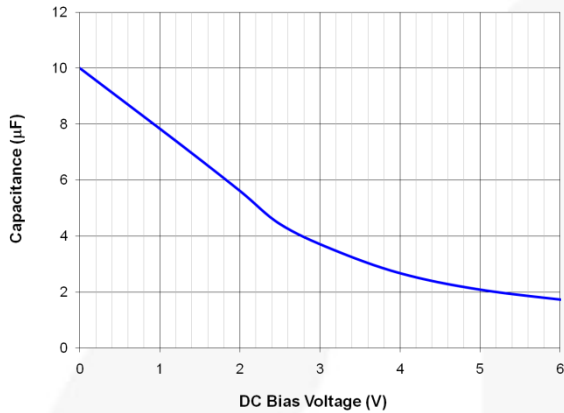
### Over-Temperature

The regulator shuts down if the die temperature exceeds 150°C. Restart occurs when the IC has cooled by approximately 20°C.

## Application Information

### Output Capacitance (C<sub>OUT</sub>)

The effective capacitance (C<sub>EFF</sub><sup>(5)</sup>) of small, high-value ceramic capacitors decreases as the bias voltage increases, as illustrated in Figure 18.



**Figure 18. C<sub>EFF</sub> for 10 µF, 0402, X5R, 6.3 V-Rated Capacitor (TDK C1005X5R0J106M050BC)**

FAN48611 is guaranteed for stable operation with the minimum value of C<sub>EFF</sub> (C<sub>EFF(MIN)</sub>) outlined in Table 4

**Table 4. Minimum C<sub>EFF</sub> Required for Stability**

Operating Conditions			C <sub>EFF(MIN)</sub> (µF)
V <sub>OUT</sub> (V)	V <sub>IN</sub> (V)	I <sub>LOAD</sub> (mA)	
5.25	2.7 to 4.8	0 to 350	6.0

**Note:**

- C<sub>EFF</sub> varies by manufacturer, capacitor material, and case size.

### Inductor Selection

Recommended nominal inductance value is 1 µH.

The FAN48611 employs valley-current limiting, so peak inductor current can reach 1.2 A for a short duration during overload conditions. Saturation causes the inductor current ripple to increase under high loading, as only the valley of the inductor current ripple is controlled.

### Startup

Input current limiting is active during soft-start, which limits the current available to charge C<sub>OUT</sub> and any additional capacitance on the V<sub>OUT</sub> line. If the output fails to achieve regulation within the limits described in the Soft-Start section above, a fault occurs, causing the circuit to shut down. It waits about 20 ms before attempting a restart. If the total combined output capacitance is very high, the circuit may not start on the first attempt, but eventually achieves regulation if no load is present. If a high current load and high capacitance are both present during soft-start, the circuit may fail to achieve regulation and continually attempt soft-start, only to have the output capacitance discharged by the load when in Fault State.

### Output Voltage Ripple

Output voltage ripple is inversely proportional to C<sub>OUT</sub>. During t<sub>ON</sub>, when the boost switch is on, all load current is supplied by C<sub>OUT</sub>.

$$V_{RIPPLE(P-P)} = t_{ON} \cdot \frac{I_{LOAD}}{C_{OUT}} \quad (1)$$

and

$$t_{ON} = t_{SW} \cdot D = t_{SW} \cdot \left(1 - \frac{V_{IN}}{V_{OUT}}\right) \quad (2)$$

therefore:

$$V_{RIPPLE(P-P)} = t_{SW} \cdot \left(1 - \frac{V_{IN}}{V_{OUT}}\right) \cdot \frac{I_{LOAD}}{C_{OUT}} \quad (3)$$

$$t_{SW} = \frac{1}{f_{SW}} \quad (4)$$

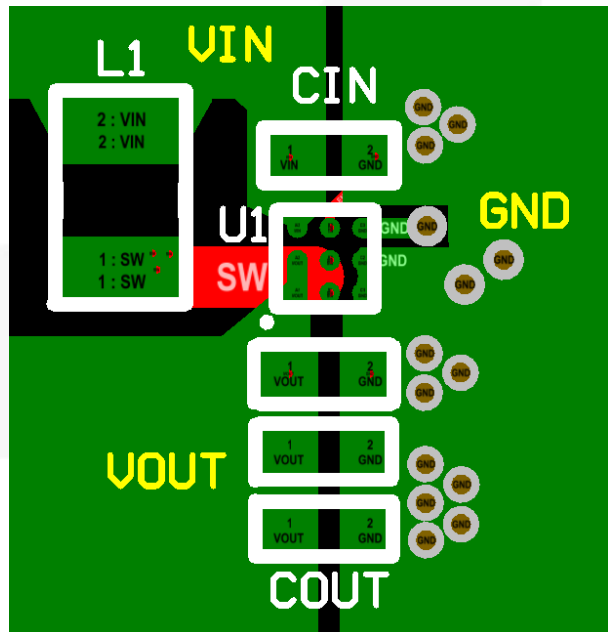
The maximum V<sub>RIPPLE</sub> occurs when V<sub>IN</sub> is minimum and I<sub>LOAD</sub> is maximum. For better ripple performance, more output capacitance can be added.

### Layout Recommendations

The layout recommendations below highlight various top-copper pours by using different colors.

To minimize spikes at V<sub>OUT</sub>, C<sub>OUT</sub> must be placed as close as possible to PGND and V<sub>OUT</sub>, as shown below.

For best thermal performance, maximize the pour area for all planes other than SW. The ground pour, especially, should fill all available PCB surface area and be tied to internal layers with a cluster of thermal vias.



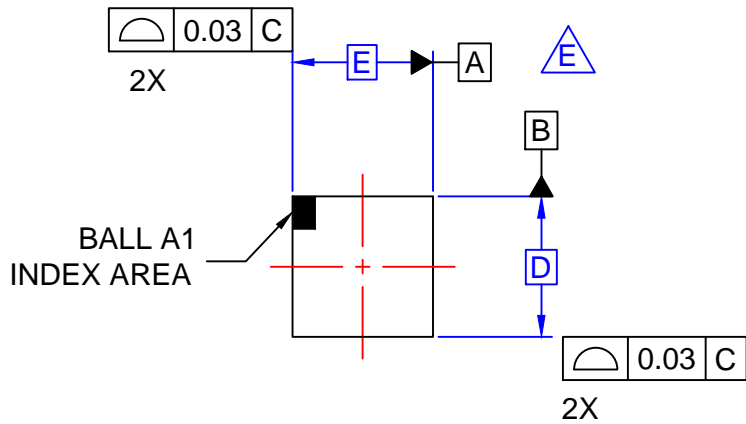
**Figure 19. Layout Recommendation**

The table below pertains to the Package information on the following page.

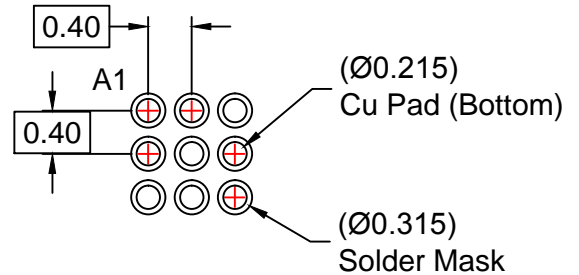
**Table 5. Product-Specific Dimensions**

D	E	X	Y
1.215 ±0.030 mm	1.215 ±0.030 mm	0.02075 mm	0.02075 mm

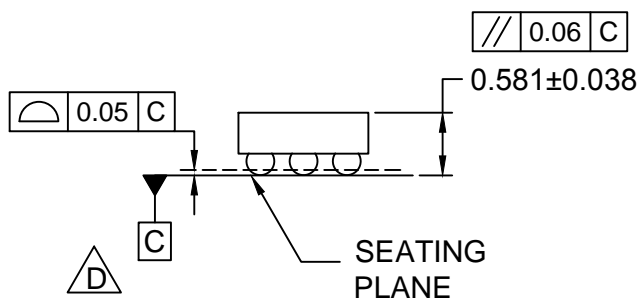




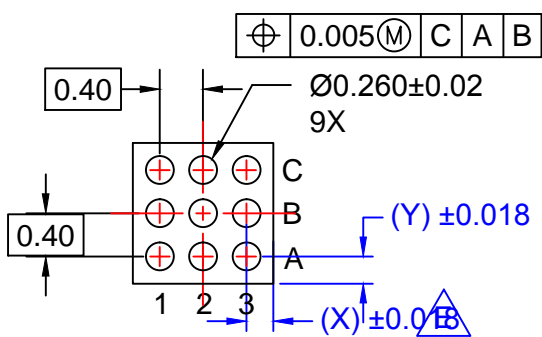
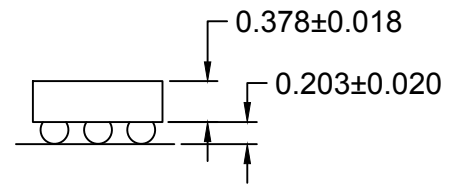
TOP VIEW



RECOMMENDED LAND PATTERN  
(NSMD PAD TYPE)



SIDE VIEWS



BOTTOM VIEW

NOTES

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 2009.
- D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.
- F. DRAWING FILNAME: MKT-UC009Ak rev2





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